

v04.0607



MMIC VCO w/ BUFFER AMPLIFIER, 5.8 - 6.8 GHz

#### Typical Applications

Low noise MMIC VCO w/Buffer Amplifier for C-Band applications such as:

- UNII & Pt. to Pt. Radios
- 802.11a & HiperLAN WLAN
- VSAT Radios

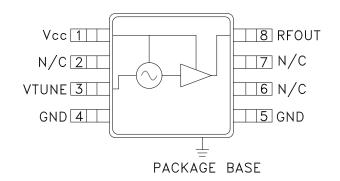
#### **Features**

Pout: +11 dBm

Phase Noise: -110 dBc/Hz @100 KHz

No External Resonator Needed Single Supply: 3V @ 100 mA 15mm<sup>2</sup> MSOP8G SMT Package

#### **Functional Diagram**



#### **General Description**

The HMC358MS8G & HMC358MS8GE are GaAs InGaP Heterojunction Bipolar Transistor (HBT) MMIC VCOs. The HMC358MS8G & HMC358MS8GE integrate resonators, negative resistance devices, varactor diodes, and buffer amplifiers. The VCO's phase noise performance is excellent over temperature, shock, and process due to the oscillator's monolithic structure. Power output is 11 dBm typical from a 3V supply voltage. The voltage controlled oscillator is packaged in a low cost, surface mount 8 lead MSOP package with an exposed base for improved RF and thermal performance.

#### Electrical Specifications, $T_A = +25^{\circ}$ C, Vcc = +3V

Parameter	Min.	Тур.	Max.	Units
Frequency Range	5.8 - 6.8		GHz	
Power Output	8	11		dBm
SSB Phase Noise @ 100 kHz Offset, Vtune= +5V @ RF Output		-110		dBc/Hz
Tune Voltage (Vtune)	0		10	V
Supply Current (Icc)		100		mA
Tune Port Leakage Current (Vtune= 10V)			10	μА
Output Return Loss		9		dB
Harmonics 2nd 3rd		-10 -20		dB dB
Pulling (into a 2.0:1 VSWR)		10		MHz pp
Pushing @ Vtune= +3V		150		MHz/V
Frequency Drift Rate		0.8		MHz/°C

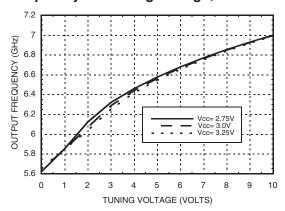


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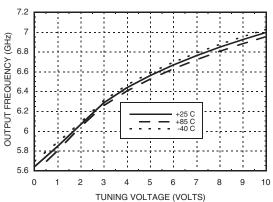


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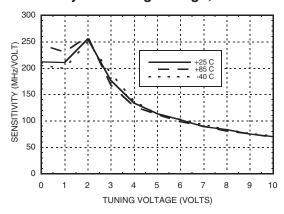
#### Frequency vs. Tuning Voltage, T= 25°C



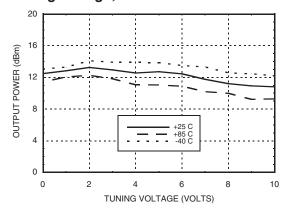
#### Frequency vs. Tuning Voltage, Vcc= +3V



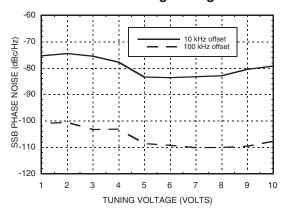
#### Sensitivity vs. Tuning Voltage, Vcc= +3V



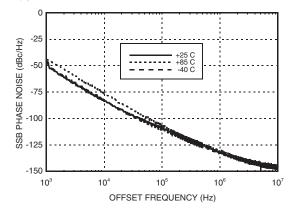
## Output Power vs. Tuning Voltage, Vcc= +3V



#### Phase Noise vs. Tuning Voltage



#### Typical SSB Phase Noise @ Vtune= +5V





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### MMIC VCO w/ BUFFER AMPLIFIER, 5.8 - 6.8 GHz

#### **Absolute Maximum Ratings**

Vcc	3.5 Vdc
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
Vtune	0 to 11V
ESD Sensitivity (HBM)	Class 1A

#### Typical Supply Current vs. Vcc

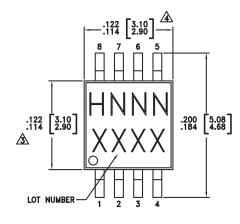
Vcc (V)	Icc (mA)
2.75	80
3.0	100
3.25	115

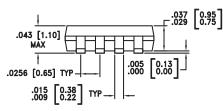
Note: VCO will operate over full voltage range shown above.

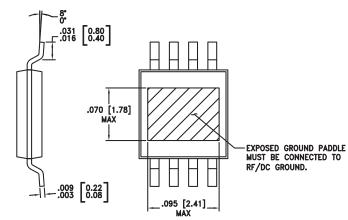


ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

#### **Outline Drawing**







#### NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- A. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 5. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

#### Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC358MS8G	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H358 XXXX
HMC358MS8GE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	<u>H358</u> XXXX

- [1] Max peak reflow temperature of 235  $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX



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#### **Pin Descriptions**

Pin Number	Function	Description	Interface Schematic
1	Vcc	Supply Voltage Vcc= 3V	Vcc O26pF
2, 6, 7	N/C	No Connection	
3	VTUNE	Control Voltage Input. Modulation port bandwidth dependent on drive source impedance.	7.5nH 150n VTUNEO
4, 5	GND	Package bottom has an exposed metal paddle that must be RF & DC grounded.	GND =
8	RFOUT	RF output (AC coupled).	RFOUT

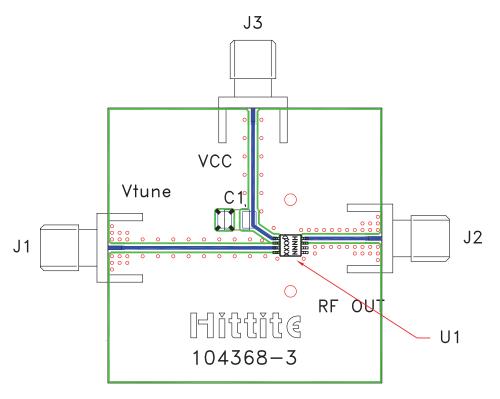


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#### **Evaluation PCB**



#### List of Materials for Evaluation PCB 104713 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
C1	10 μF Tantalum Capacitor
U1	HMC358MS8G / HMC358MS8GE VCO
PCB [2]	104368 Eval Board

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.